2SD2420, 2SD2420A

Silicon NPN triple diffusion planar type darlington

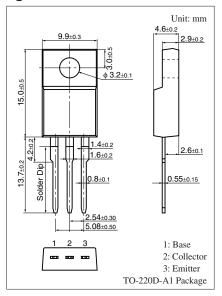
For power amplification Complementary to 2SB1623, 2SB1623A

■ Features

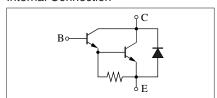
- High forward current transfer ratio h_{FE}
- Dielectric breakdown voltage of the package: > 5 kV

■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage	2SD2420	V_{CBO}	60	V
(Emitter open)	2SD2420A		80	
Collector-emitter voltage	2SD2420	V _{CEO}	60	V
(Base open)	2SD2420A		80	
Emitter-base voltage (Col	V_{EBO}	5	V	
Collector current	I_C	4	A	
Peak collector current	I_{CP}	8	A	
Collector power	P _C	30	W	
dissipation	$T_a = 25^{\circ}C$		2.0	
Junction temperature	T_{j}	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	



Internal Connection



\blacksquare Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)		V _{CEO}	$I_C = 30 \text{ mA}, I_B = 0$	60			V
Base-emitter voltage		V_{BE}	$V_{CE} = 3 \text{ V}, I_{C} = 3 \text{ A}$			2.5	V
Collector-base cutoff	2SD2420	I_{CBO}	$V_{CB} = 60 \text{ V}, I_{E} = 0$			200	μΑ
current (Emitter open)	2SD2420A		$V_{CB} = 80 \text{ V}, I_{E} = 0$			200	
Collector-emitter cutoff	2SD2420	I_{CEO}	$V_{CE} = 30 \text{ V}, I_{B} = 0$			500	μΑ
current (Base open)	2SD2420A		$V_{CE} = 40 \text{ V}, I_{B} = 0$			500	
Emitter-base cutoff current (Collector open)		I_{EBO}	$V_{EB} = 5 \text{ V}, I_{C} = 0$			2	mA
Forward current transfer rat	io	h _{FE1}	$V_{CE} = 3 \text{ V}, I_{C} = 0.5 \text{ A}$	1 000			_
		h _{FE2} *	$V_{CE} = 3 \text{ V}, I_{C} = 3 \text{ A}$	2000		10 000	
Collector-emitter saturation voltage		V _{CE(sat)1}	$I_C = 3 \text{ A}, I_B = 12 \text{ mA}$			2.0	V
		V _{CE(sat)2}	$I_C = 5 \text{ A}, I_B = 20 \text{ mA}$			4.0	
Transition frequency		f_T	$V_{CE} = 10 \text{ V}, I_{C} = 0.5 \text{ A}, f = 1 \text{ MHz}$		20		MHz
Turn-on time		t _{on}	$I_C = 3 \text{ A}, I_{B1} = 12 \text{ mA}, I_{B2} = -12 \text{ mA}$		0.5		μs
Storage time		t _{stg}	$V_{CC} = 50 \text{ V}$		4.0		μs
Fall time		$t_{\rm f}$			1.0		μs

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	Q	Р		
h _{FE2}	2000 to 5000	4000 to 10000		

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